

To our customers,

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April 1<sup>st</sup>, 2010  
Renesas Electronics Corporation

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## BIPOLAR ANALOG INTEGRATED CIRCUIT

# $\mu$ PC3228T5S

### LOW DISTORTION DOWN-CONVERTER + AGC AMPLIFIER + VIDEO AMPLIFIER

#### DESCRIPTION

The  $\mu$ PC3228T5S is a silicon bipolar monolithic IC designed for use as IF down-converter for digital TV, digital CATV. This IC consists of AGC amplifier, mixer and video amplifier.

The package is 32-pin plastic QFN (Quad Flat Non-lead) package suitable for surface mount.

This IC is manufactured using our 30 GHz  $f_{\max}$  UHS0 (Ultra High Speed Process) silicon bipolar process.

This process uses silicon nitride passivation film. This material can protect chip surface from external pollution and prevent corrosion/migration. Thus, this IC has excellent performance, uniformly and reliability.

#### FEATURES

- Total performance :  $I_{CC} = 85 \text{ mA TYP. @ } V_{CC} = 5 \text{ V}$
- AGC AMPLIFIER + MIXER + DRIVER BLOCK :  $f_{RF} \text{ (BW)} = 20 \text{ to } 800 \text{ MHz}$   
 :  $CG = 28 \text{ dB TYP.}$   
 :  $GCR = 70 \text{ dB TYP.}$   
 :  $IM_3 = 47 \text{ dBc MIN./57 dBc TYP. @ Single Ended-OUT} = 0.5 \text{ V}_{p-p}/\text{tone}$
- VIDEO AMPLIFIER BLOCK :  $G_V = 59 \text{ dB TYP.}$   
 :  $f_{IF} \text{ (BW)} = 20 \text{ to } 100 \text{ MHz}$   
 :  $IM_3 = 45 \text{ dBc MIN./55 dBc TYP. @ Output} = 110 \text{ dBu/tone, Differential-out}$
- High-density surface mounting : 32-pin plastic QFN package ( $5.0 \times 5.0 \times 0.75 \text{ mm}$ )

#### APPLICATION

- Digital CATV
- Cable modem receivers

#### ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
$\mu$ PC3228T5S-E2	$\mu$ PC3228T5S-E2-A	32-pin plastic QFN (Pb-Free)	C3228	<ul style="list-style-type: none"> <li>• Embossed tape 12 mm wide</li> <li>• Pin 8,9 face the perforation side of the tape</li> <li>• Qty 2.5 kpcs/reel</li> <li>• Dry pack specification</li> </ul>

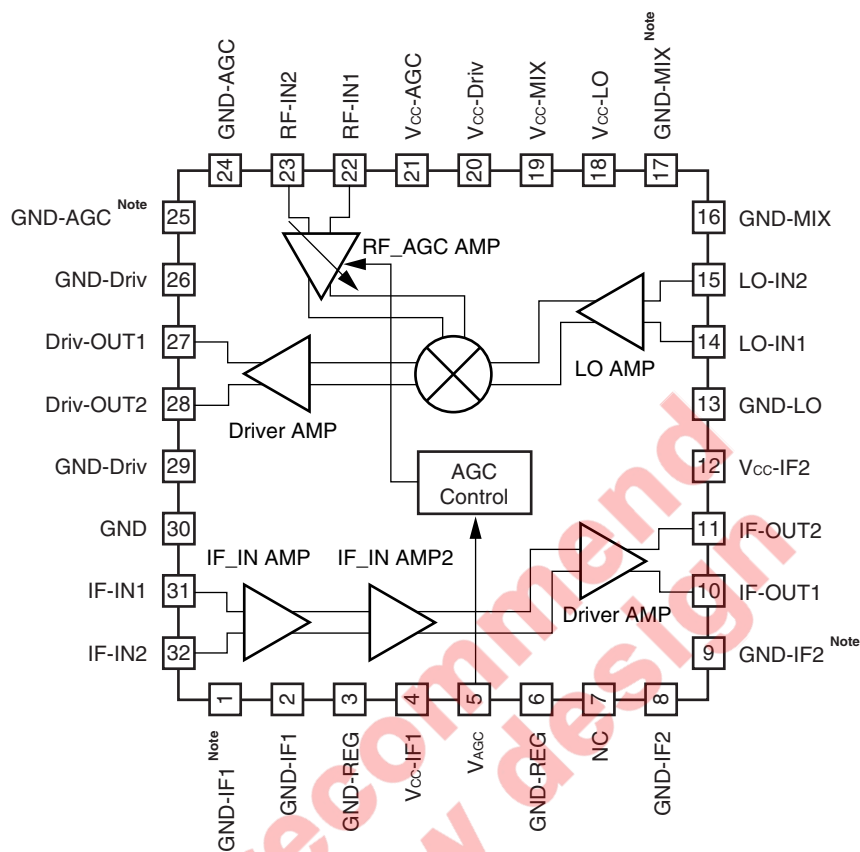
**Remark** To order evaluation samples, contact your nearby sales office.  
 Part number for sample order:  $\mu$ PC3228T5S

**Caution** Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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# INTERNAL BLOCK DIAGRAM AND PIN CONFIGURATION

(Top View)



**Note** 1, 9, 17, 25-pin: Connected to the lead frame.

# ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Conditions	Ratings	Unit
Supply Voltage	V <sub>CC</sub>	T <sub>A</sub> = +25°C	6.0	V
Power Dissipation	P <sub>D</sub>	T <sub>A</sub> = +80°C <b>Note</b>	800	mW
Operating Ambient Temperature	T <sub>A</sub>	<b>Note</b>	–20 to +80	°C
Storage Temperature	T <sub>stg</sub>		–55 to +150	°C

**Note** Mounted on double-sided copper-clad 50 × 50 × 1.6 mm epoxy glass PWB

# RECOMMENDED OPERATING RANGE (T<sub>A</sub> = +25°C, unless otherwise specified)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Supply Voltage	V <sub>CC</sub>		4.5	5.0	5.5	V
Operating Ambient Temperature	T <sub>A</sub>	V <sub>CC</sub> = 4.5 to 5.5 V	–20	+25	+80	°C
Gain Control Voltage Range	V <sub>AGC</sub>		0	–	3.3	V
RF Operating Frequency Range	f <sub>RF</sub> (BW)		20	–	800	MHz
IF Operating Frequency Range	f <sub>IF</sub> (BW)		20	–	100	MHz

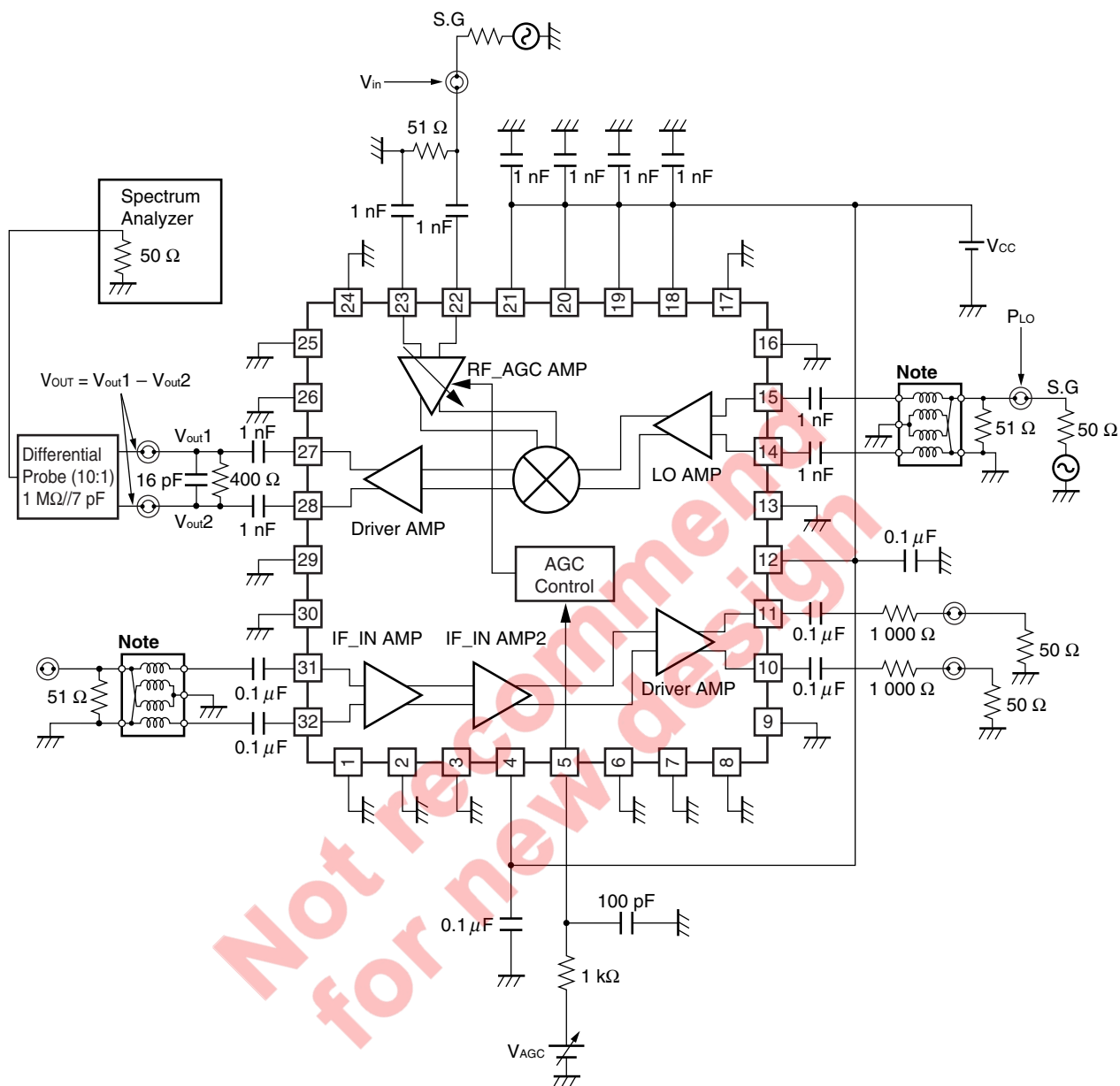
Not recommended  
for new design

**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = +25°C, V<sub>CC</sub> = 5 V, unless otherwise specified)**

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
<b>DC Characteristics</b>						
Circuit Current	I <sub>CC</sub>	No input signal <b>Note 1</b>	65	85	110	mA
AGC Voltage High Level	V <sub>AGC (H)</sub>	@ Maximum gain <b>Note 1</b>	2.5	–	3.5	V
AGC Voltage Low Level	V <sub>AGC (L)</sub>	@ Minimum gain <b>Note 1</b>	–	0	–	V
<b>RF Characteristics</b> (RF AGC Amplifier Block + Mixer Block + Driver Amplifier: f <sub>RF</sub> = 80 MHz, f <sub>LO</sub> = 130 MHz, P <sub>LO</sub> = –10 dBm, Z <sub>S</sub> = 50 Ω, Z <sub>L</sub> = 400 Ω/16 pF)						
RF Input Frequency Range	f <sub>RF</sub>	f <sub>c</sub> = –3 dB <b>Note 1</b>	20	–	800	MHz
RF Gain Control Range	GCR1	V <sub>AGC</sub> = 0 to 2.5 V <b>Note 1</b>	62	70	–	dB
Mixer Conversion Gain	CG	V <sub>AGC</sub> = 2.5 V Differential-IN: V <sub>in</sub> = +18 dBmV <b>Note 1</b>	25	28	31	dB
3rd Order Intermodulation Distortion	IM <sub>31</sub>	f <sub>1</sub> = 44 MHz, f <sub>2</sub> = 45 MHz, V <sub>in</sub> = +30 dBmV/tone, Single Ended-OUT = 0.5 V <sub>p-p</sub> /tone <b>Note 1</b>	47	57	–	dBc
Noise Figure	NF1	V <sub>AGC</sub> = 2.5 V, f = 50 MHz, Differential-Output <b>Note 2</b>	–	8.3	–	dB
<b>IF Characteristics</b> (IF Amplifier Block + Driver Amplifier: f <sub>IF</sub> = 50 MHz, Z <sub>S</sub> = 50 Ω, Z <sub>L</sub> = 2 100 Ω)						
IF Input Frequency Range	f <sub>IF</sub>	f <sub>c</sub> = –3 dB <b>Note 5</b>	20	–	100	MHz
IF Amplifier Gain	G <sub>v</sub>	V <sub>in</sub> = –7 dBmV, Differential-IN/OUT <b>Note 5</b>	56	59	62	dB
3rd Order Intermodulation Distortion	IM <sub>32</sub>	f <sub>1</sub> = 49.5 MHz, f <sub>2</sub> = 50.5 MHz, V <sub>out</sub> = 110 dBu/tone, Differential-IN/OUT <b>Note 5</b>	45	55	–	dBc
IF Output Voltage	V <sub>out</sub>	Single Ended-Output <b>Note 5</b>	–	1.0	–	V <sub>p-p</sub>
Noise Figure	NF2	V <sub>AGC</sub> = 0 V, f = 50 MHz, Single Ended-Output <b>Note 2</b>	–	3.0	–	dB
<b>Total Block (RF AGC Amplifier + Mixer + Driver Amplifier + SAW Filter + IF Amplifier + Driver Amplifier), SAW Filter : EPCOS X6889M (f<sub>IF</sub> = 49 MHz, P<sub>LO</sub> = –10 dBm, f<sub>RF</sub> = 70 to 130 MHz, Z<sub>S</sub> = 50 Ω, Z<sub>L</sub> = 1 050 Ω)</b>						
LO-RF Leakage	LO <sub>RF</sub>	V <sub>AGC</sub> = 2.5 V, 22-pin 75 Ω Termination f <sub>LO</sub> = 110 to 180 MHz <b>Note 3</b>	–	–54	–44	dBmV
LO-IF Leakage	LO <sub>IF</sub>	V <sub>AGC</sub> = 2.5 V, V <sub>out</sub> = 0.7 V <sub>p-p</sub> Single Ended-Output f <sub>RF</sub> = 130 MHz, f <sub>LO</sub> = 179 MHz <b>Note 4</b>	–	–40	–25	dBc

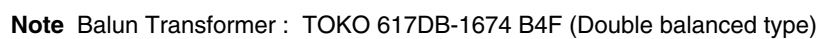
- Notes**
1. By measurement circuit 1
  2. By measurement circuit 2
  3. By measurement circuit 3
  4. By measurement circuit 4
  5. By measurement circuit 5

# MEASUREMENT CIRCUIT 1



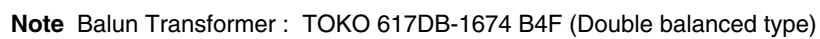
**Note** Balun Transformer : TOKO 617DB-1674 B4F (Double balanced type)

## Noise Figure





## Lo-RF Leakage



( $f_{RF} = 70$  to  $130$  MHz ( $f_{IF} = 49.1$  MHz  $\pm$  0.6 MHz),  $f_{LO} = 119$  to  $179$  MHz,  $P_{LO} = -10$  dBm,  $V_{out} = 0.7$  V<sub>p-p</sub> (Single Ended))

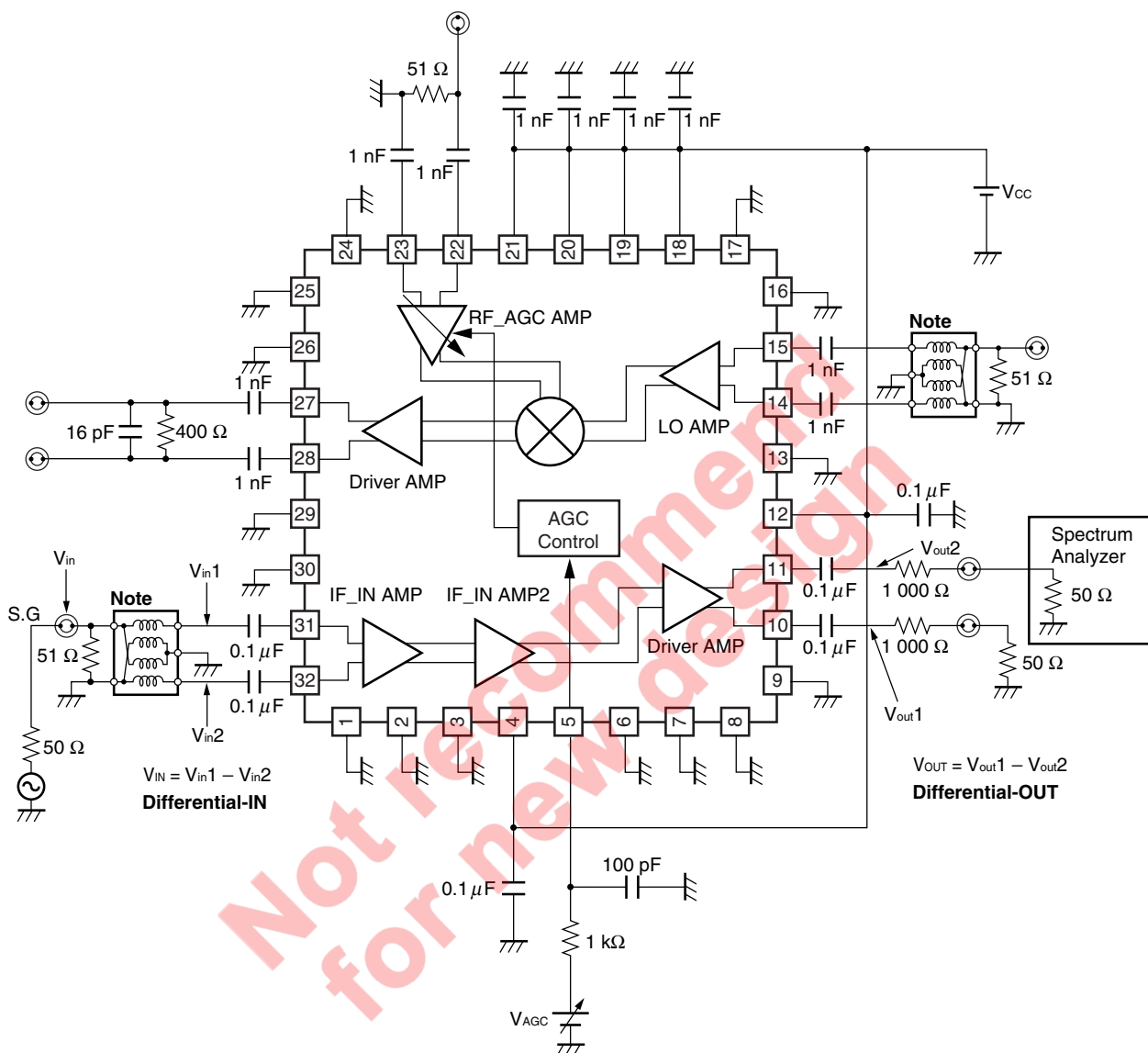
The schematic diagram illustrates the internal architecture of the AD6655 evaluation board. Key components and connections include:

- Input Section:** The input signal  $V_{in}$  is connected to pin 24 through a 51  $\Omega$  resistor and a 1 nF capacitor. The output of this stage is connected to pin 23.
- RF\_AGC AMP:** The RF\_AGC AMP is connected to pins 23, 22, 21, 20, 19, 18, and 17. It is biased by  $V_{CC}$  and has a 1 nF capacitor connected to pin 21.
- Driver AMP:** The Driver AMP is connected to pins 27, 28, 29, and 30. It is biased by  $V_{CC}$  and has a 1 nF capacitor connected to pin 27.
- LO AMP:** The LO AMP is connected to pins 15, 14, 13, and 12. It is biased by  $V_{CC}$  and has a 1 nF capacitor connected to pin 15.
- AGC Control:** The AGC Control block is connected to pins 12, 11, 10, and 9. It is biased by  $V_{CC}$  and has a 0.1  $\mu$ F capacitor connected to pin 12.
- IF\_IN AMP and IF\_IN AMP2:** The IF\_IN AMP is connected to pins 31 and 32. The IF\_IN AMP2 is connected to pins 1, 2, 3, 4, 5, 6, 7, and 8. Both are biased by  $V_{CC}$  and have 0.1  $\mu$ F capacitors connected to pins 31 and 32.
- SAW Filter:** The SAW Filter EPCOS X6889M is connected to pins 28 and 31.
- Output Section:** The output signal  $V_{out1}$  is connected to pin 11 through a 1000  $\Omega$  resistor and a 0.1  $\mu$ F capacitor. The output signal  $V_{out2}$  is connected to pin 10 through a 1000  $\Omega$  resistor and a 0.1  $\mu$ F capacitor. The output is connected to a Spectrum Analyzer.
- Other Components:** The diagram includes a 51  $\Omega$  resistor, 1 nF capacitors, 0.1  $\mu$ F capacitors, 100 pF capacitor, 1 k  $\Omega$  resistor, and a Spectrum Analyzer.

Data Sheet PU10623EJ01V0DS

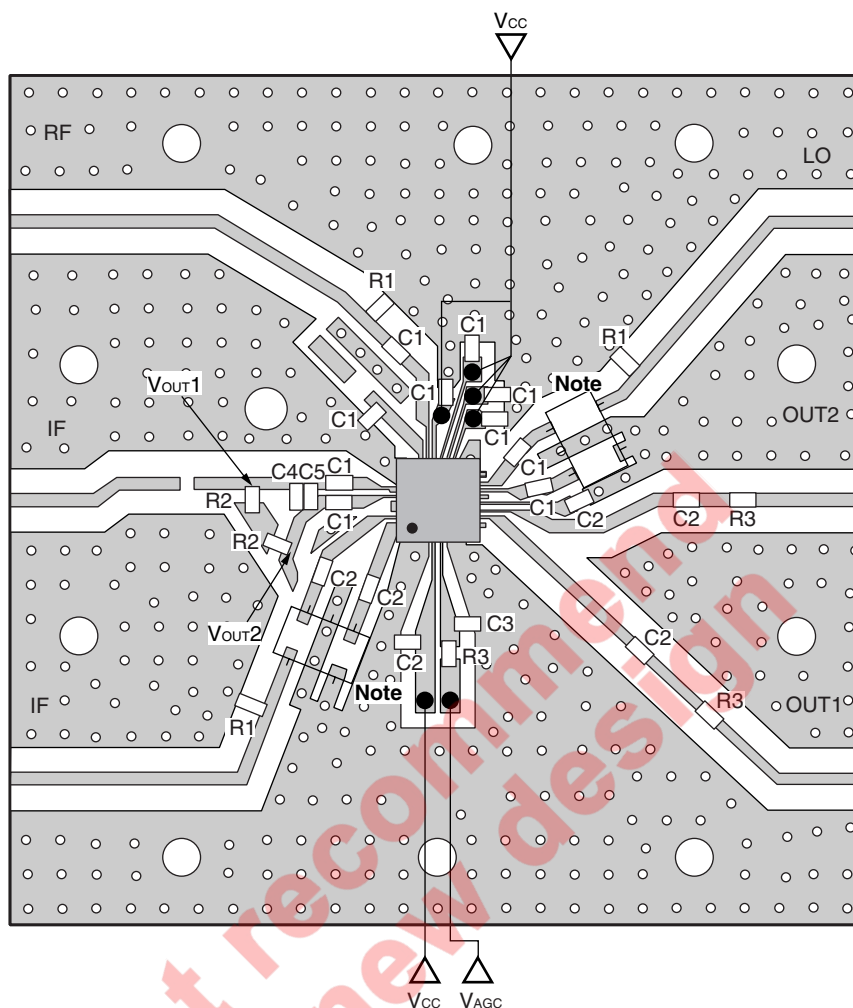
# MEASUREMENT CIRCUIT 5

IF Block



**Note** Balun Transformer : TOKO 617DB-1674 B4F (Double balanced type)

# ILLUSTRATION OF THE EVALUATION BOARD



**Note** Balun Transformer : TOKO 617DB-1674 B4F (Double balanced type)

## Remarks

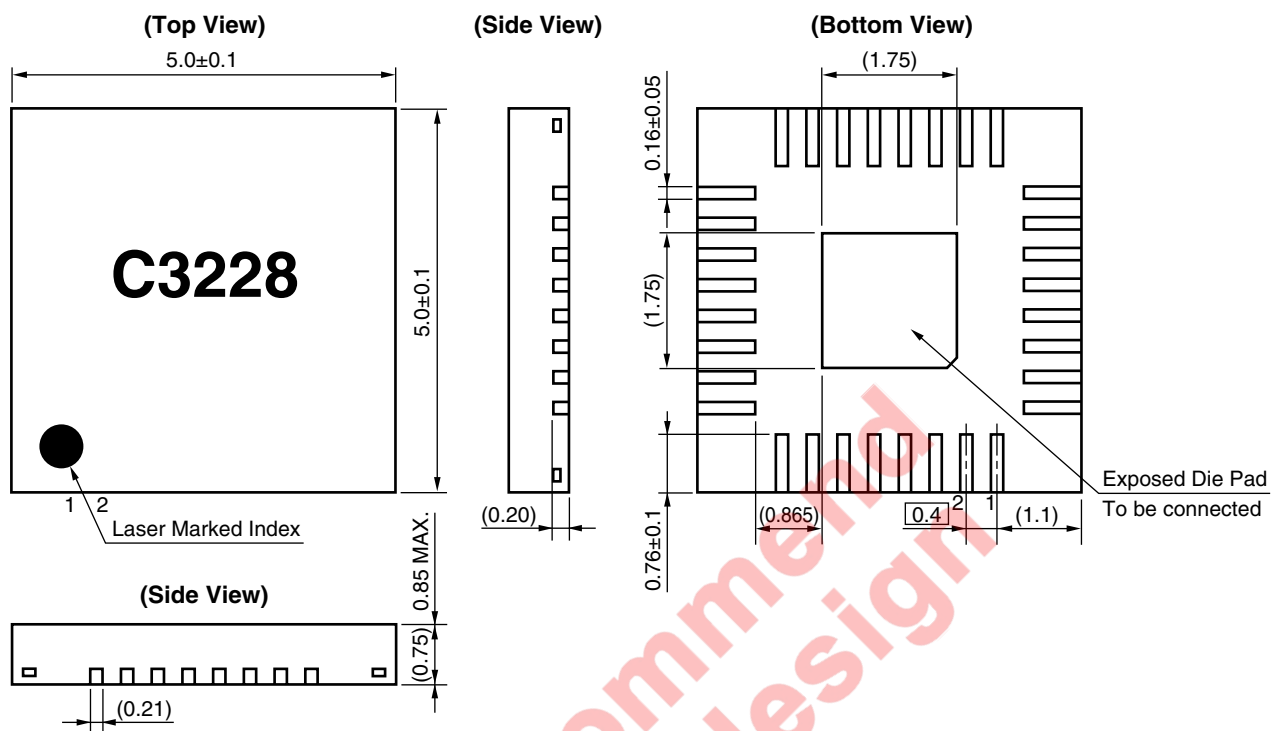
1. Back side: GND pattern
2. Solder plated on pattern
3.  $\circ$  : Through hole

## USING THE NEC EVALUATION BOARD

Symbol	Values	Maker	Part Number	Size
C1	1 nF	Murata	GRM39CH	1608
C2	0.1 $\mu$ F	Murata	GRM39B	1608
C3	100 pF	Murata	GRM39CH	1608
C4	10 pF	Murata	GRM36B	1005
C5	6 pF	Murata	GRM36B	1005
R1	51 $\Omega$	Susumu	RR0816 510SSM	1608
R2	200 $\Omega$	Susumu	RR0816 201SSM	1608
R3	1 000 $\Omega$	Susumu	RR0816 102SSM	1608

PACKAGE DIMENSIONS

32-PIN PLASTIC QFN (UNIT: mm)



**NOTES ON CORRECT USE**

- (1) Observe precautions for handling because of electro-static sensitive devices.
- (2) Form a ground pattern as widely as possible to minimize ground impedance (to prevent undesired oscillation).  
All the ground terminals must be connected together with wide ground pattern to decrease impedance difference.
- (3) The bypass capacitor should be attached to V<sub>CC</sub> line.

**RECOMMENDED SOLDERING CONDITIONS**

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) : 260°C or below Time at peak temperature : 10 seconds or less Preheating temperature (package surface temperature) : 120°C or below Maximum number of flow processes : 1 time Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	HS350

**Caution** Do not use different soldering methods together (except for partial heating).

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